



Product Change Notification: CAAN-260ITF774

Date:

17-Jul-2026

Product Category:

8-Bit Microcontrollers

Notification Subject:

CCB 7967 Final Notice: Qualification of MTAI as an additional assembly site for selected PIC16F15213, PIC16F15214, PIC16F17114, PIC16F17115, PIC16F18013, PIC16F18014, PIC16F18114 and PIC16F18115 device families available in 8L DFN (4x4x0.9mm) and 8L DFN (3x3x0.9mm) packages.

Affected CPNs:

[CAAN-260ITF774_Affected_CPN_07172026.pdf](#)

[CAAN-260ITF774_Affected_CPN_07172026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for selected PIC16F15213, PIC16F15214, PIC16F17114, PIC16F17115, PIC16F18013, PIC16F18014, PIC16F18114 and PIC16F18115 device families available in 8L DFN (4x4x0.9mm) and 8L DFN (3x3x0.9mm) packages.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Microchip Technology Thailand	Microchip Technology Thailand	Microchip Technology Thailand (HQ) (MTAI)	Yes

	(Branch) (MMT)		(Branch) (MMT)			
Wire Material	Au	CuPdAu	Au	CuPdAu	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)		QMI519 (PFAS-free)		QMI519 (PFAS-free)	No
Molding Compound Material	G700LTD		G700LTD		G700LTD	No
Lead-Frame Material	A194		A194		A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 15 August 2026 (date code: 2633)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	November 2025					>	July 2026					August 2026				
Work Week	45	46	47	48	49		27	28	29	30	31	32	33	34	35	36
Initial PCN Issue Date					x											
Qual Report Availability									x							
Final PCN Issue Date									x							
Estimated Implementation Date													x			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as

PCN_#_Qual_Report.

Revision History: November 30, 2025: Issued initial notification.

July 17, 2026: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 15, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CAAN-260ITF774 Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PIC16F15213-I/MF
PIC16F15214-E/MF
PIC16F15213-E/MF
PIC16F18013-E/MF
PIC16F18014-E/MF
PIC16F18014T-I/MF
PIC16F18013T-I/MF
PIC16F18014-I/MF
PIC16F18013-I/MF
PIC16F17115T-I/MD
PIC16F17114T-I/MD
PIC16F18115T-I/MD
PIC16F18115-I/MD
PIC16F17115-I/MD
PIC16F18114-I/MD
PIC16F18115-E/MD
PIC16F17115-E/MD
PIC16F18114T-I/MD
PIC16F17114-I/MD
PIC16F17114-E/MD
PIC16F18114-E/MD
PIC16F15213T-E/MF
PIC16F15214T-I/MF
PIC16F15213T-I/MF
PIC16F15214-I/MF



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CAAN-26OITF774

Date: July 6, 2026

Qualification of MTAI as an additional assembly site for selected PIC16F15213, PIC16F15214, PIC16F17114, PIC16F17115, PIC16F18013, PIC16F18014, PIC16F18114 and PIC16F18115 device families available in 8L DFN (4x4x0.9mm) and 8L DFN (3x3x0.9mm) packages.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MTAI as an additional assembly site for selected PIC16F15213, PIC16F15214, PIC16F17114, PIC16F17115, PIC16F18013, PIC16F18014, PIC16F18114 and PIC16F18115 device families available in 8L DFN (4x4x0.9mm) and 8L DFN (3x3x0.9mm) packages.

CN: E000292970
QUAL ID: R2600457 Rev A
MP CODE: 59B0G4M8XFB1
Part No.: PIC16F17114-E/MD
Bonding No.: BD-003997
CCB No.: 7967

Lead Frame

Paddle Size: 114x146 mils
Material: A194
DAP Surface Prep: Ag-Selective plated
Process: Etched
Lead Lock: Yes
Part Number: 10100845
Plating Composition: Matte Tin

Bond Wire

Wire: CuPdAu wire

Die Attach Material

Epoxy: QMI519 (PFAS free)
Conductive: Yes

Mold Compound

Mold Compound: G700LTD

Package

Type: DFN
Pin/Ball Count: 8L
Package Size: 4x4x0.9 mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.
MTAI270200008.000
MTAI270200809.000
MTAI270200812.000

Result: **Pass**

Conclusion:

Qualification of 59B0G mask / PIC16F17114-E/MD product / CuPdAu wire in 8L DFN 4x4x0.9mm package at MTAI site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture Soak Precondition Prior to Stresses	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C	JESD22-A113, JEDEC J-STD-020	231 units each lot / 3 lots	Electrical Results: 0/231, 0/231, 0/231	Pass	
	Electrical Test: Tester J750, 25°C, 85°C and 125°C					

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temp Storage	175°C / 500 hours	JESD22-A103	45 units each lot / 3 lots	Electrical Results: 0/45, 0/45, 0/45	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	
	Electrical Test: Tester J750, 25°C, 85°C and 125°C					

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temperature Cycling	-55°C / +150°C Air to Air / 1000 Cycles	JESD22-A104	77 units each lot / 3 lots	Electrical Results: 0/77, 0/77, 0/77	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	
	Electrical Test: Tester J750, 25°C, 85°C and 125°C					

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V	JESD22-A110	77 units each lot / 3 lots	Electrical Results: 0/77, 0/77, 0/77	Pass	
	WBP			0/3, 0/3, 0/3	Pass	
	WBS			0/3, 0/3, 0/3	Pass	
	Electrical Test: Tester J750, 25°C, 85°C and 125°C					

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Unbiased HAST	+130°C / 85%RH / 96 hours	JESD22-A118	77 units each lot / 3 lots	Electrical Results: 0/77, 0/77, 0/77	Pass	
	Electrical Test: Tester J750, 25°C					

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Solderability (0 hr.) Method 1: Dip and Look	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage	J-STD-002 / JESD22B-102	22 units / 1 lot	Visual Result: 0/22	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q100 -001	5 units / 1 lot	0/5	Pass	